



Material Content Data Sheet



Sales Product Name		TLD5190QV		Issued		24. January 2018		
MA#		MA001680146						
Package		PG-VQFN-48-31		Weight*		129.30 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	1.790	1.38	1.38	13846	13846
leadframe	inorganic material	phosphorus	7723-14-0	0.018	0.01		139	
	non noble metal	zinc	7440-66-6	0.072	0.06		554	
	non noble metal	iron	7439-89-6	1.433	1.11		11084	
wire	non noble metal	copper	7440-50-8	58.193	45.01	46.19	450074	461851
	non noble metal	copper	7440-50-8	0.635	0.49	0.49	4915	4915
	encapsulation	organic material	carbon black	1333-86-4	0.190	0.15		1469
encapsulation	plastics	epoxy resin	-	8.040	6.22		62186	
	inorganic material	silicondioxide	60676-86-0	55.080	42.60	48.97	425998	489653
leadfinish	non noble metal	tin	7440-31-5	2.596	2.01	2.01	20081	20081
plating	noble metal	silver	7440-22-4	0.614	0.47	0.47	4747	4747
glue	plastics	epoxy resin	-	0.146	0.11		1129	
	noble metal	silver	7440-22-4	0.489	0.38	0.49	3778	4907
*deviation	< 10%				Sum in total:		100.00	1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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